

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Canceled)
2. (Canceled)
3. (Canceled)
4. (Canceled)
5. (Canceled)
6. (Canceled)
7. (Canceled)
8. (Original) A component of semiconductor processing equipment, said component comprising a liquid crystalline polymer on an outer surface thereof.
9. (Original) The component according to Claim 8, wherein the liquid crystalline polymer comprises a coating on a surface of a substrate.
10. (Original) The component according to Claim 9, wherein the substrate comprises aluminum or an aluminum alloy.
11. (Original) The component according to Claim 9, wherein the substrate comprises alumina.
12. (Currently Amended) The component according to Claim 10, wherein the substrate includes an anodized ~~or non-anodized~~ surface.

13. (Original) The component according to Claim 9, wherein the liquid crystalline polymer comprises a plasma sprayed coating.
14. (Original) The component according to Claim 8, wherein the component is a plasma chamber wall, a chamber liner, a gas distribution plate, a gas ring, a pedestal, an electrostatic chuck and/or a focus ring.
15. (Original) The component according to Claim 8, wherein the liquid crystalline polymer comprises a preformed sheet covering a surface of a substrate.
16. (Original) The component according to Claim 13, wherein the component comprises a roughened surface in contact with the plasma sprayed coating.
17. (Original) The component according to Claim 8, wherein the liquid crystalline polymer contains a filler.
18. (Original) A plasma chamber comprising at least one component according to Claim 8.
19. (Canceled)
20. (Canceled)
21. (Canceled)
22. (Canceled)
23. (Canceled)